Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HP ProLiant DL320e Gen8 V2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm System board, PDB, FP board, dedicated Lan card, SFF HDD board, LFF HHD board, x8 riser,x16 riser	8
Batteries	All types including standard alkaline and lithium coin or button style batteries System Battery	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	In power supply(350W or 460W)	
External electrical cables and cords	Power cord	1
Gas Discharge Lamps	No	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	No	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos	No	0
Components, parts and materials containing	No	0

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refractory ceramic fibers		
Components, parts and materials containing radioactive substances	No	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdriver (included with the server)	T10/15
Philps screwdriver	#2

3.0 Product Disassembly Process

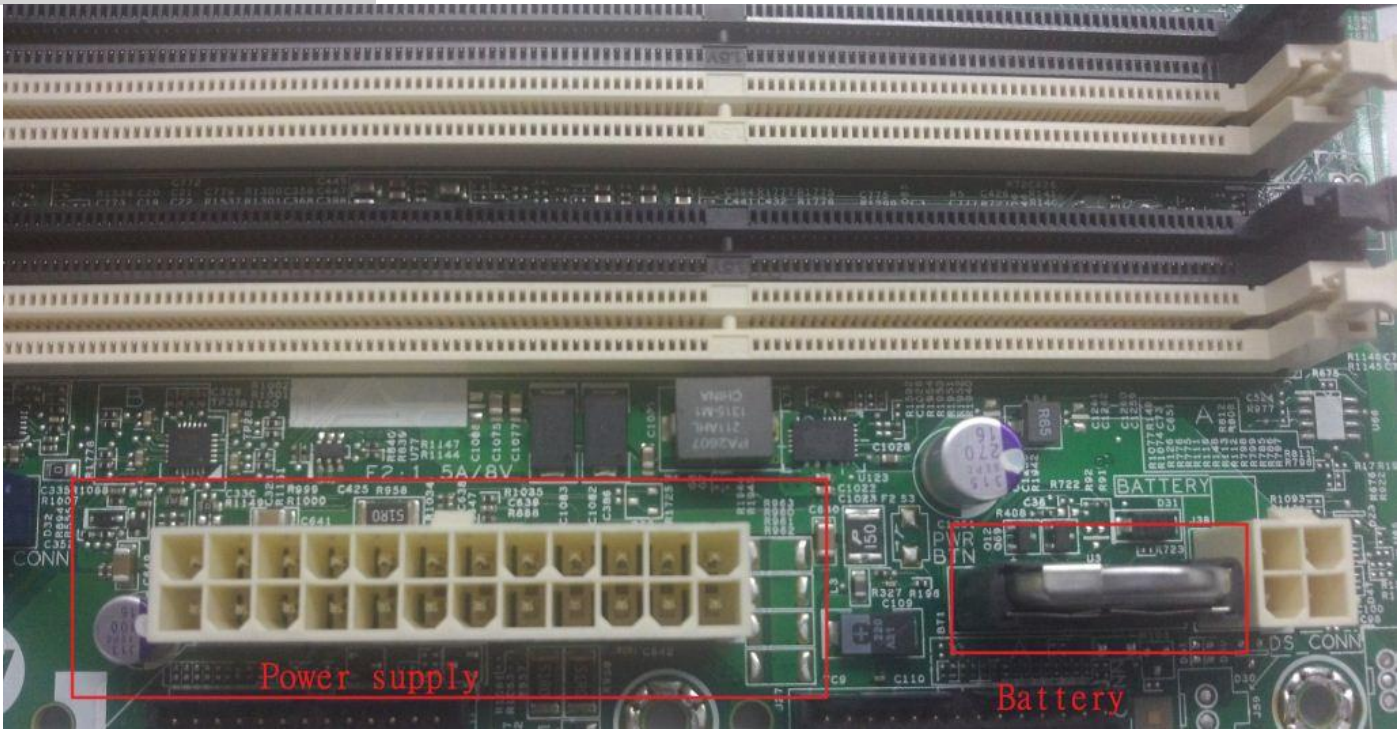
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System Board Battery - Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
2. Capacitors in 300W power supply=> 2.5 cm () - Remove the power supply from the system with a T-15 torx driver. With a #2 Philips screw driver remove the screws securing the top cover then locate the capacitors and pry from the PCB with a flat head screw driver or Long Nose Plier () and dispose of properly.
3. Capacitors in 750W power supply=> 2.5 cm () - Remove the power supply from the system with a T-15 torx driver. With a #2 Philips screw driver remove the screws securing the top cover then locate the capacitors and pry from the PCB with a flat head screw driver or Long Nose Plier and dispose of properly.
4.
5. .
6.
7.
8.

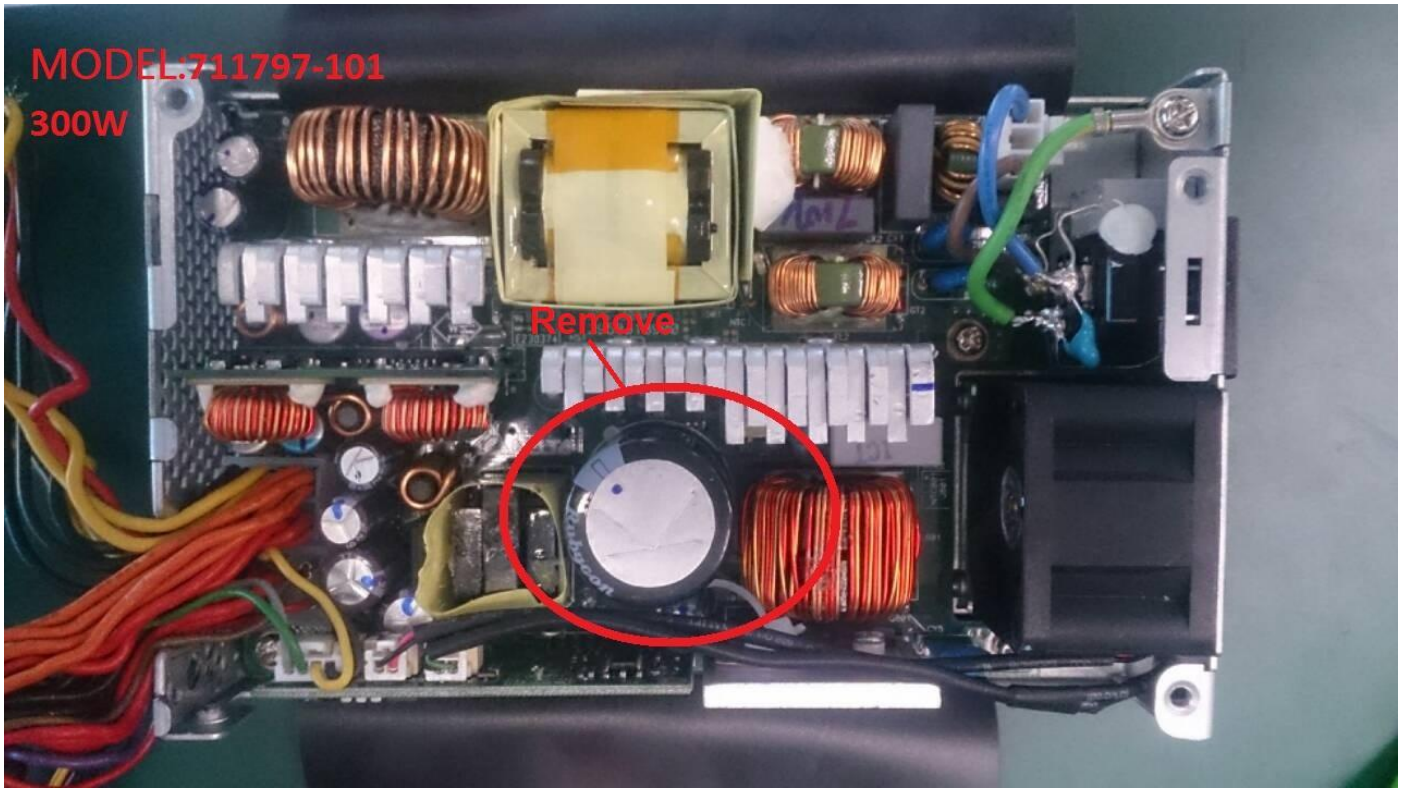
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Open the locking latch, slide the access panel to the rear of the chassis, and then remove the access panel.

RTC BATTERY



POWER SUPPLY – 300W



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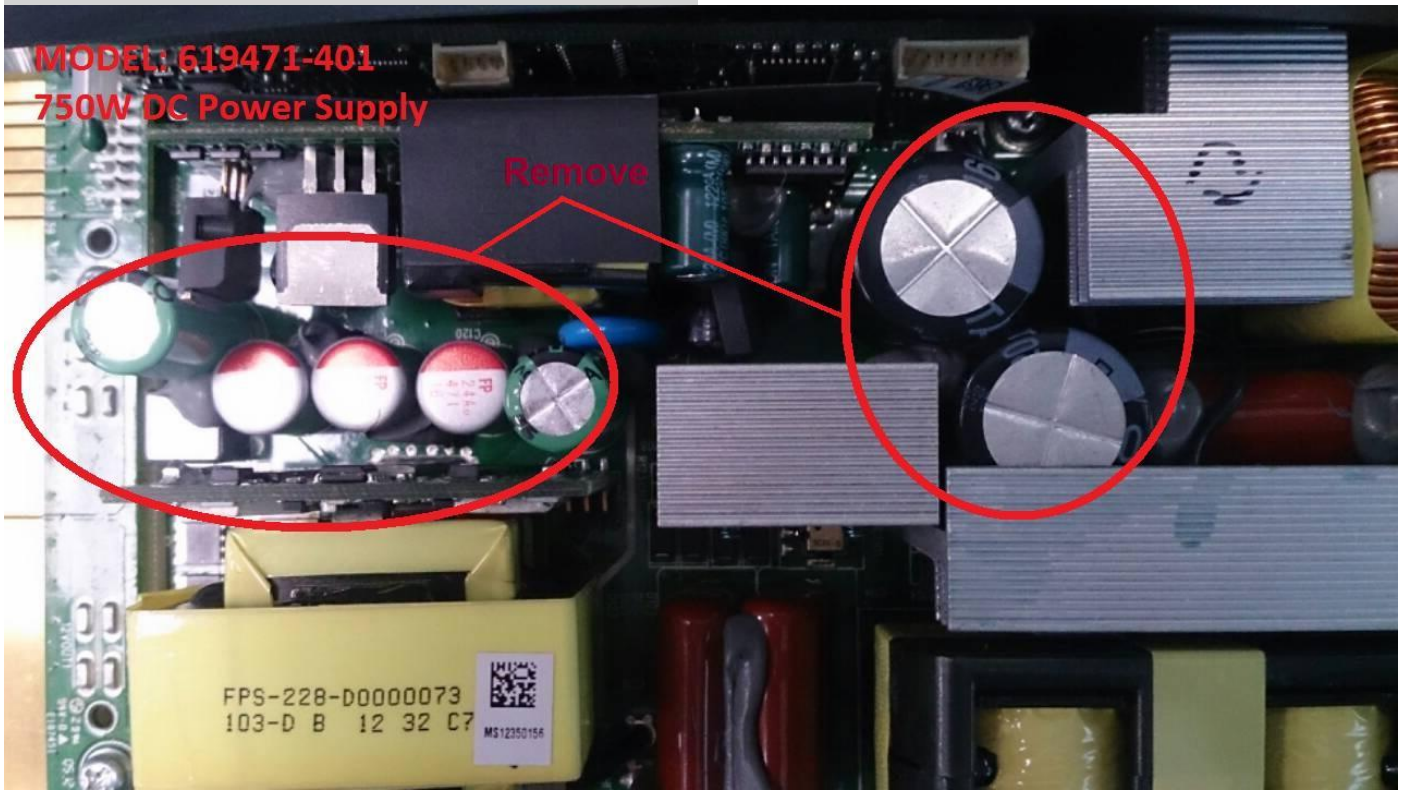
POWER SUPPLY – 750W



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